



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	23-08-2023
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Material Declaration champion	<b>Representative Title</b>	Material Declaration champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32H7R3Z8T6	E01A*485XXY	A	9991	23-08-2023
	Amount	UoM	Unit type	ST ECOPACK Grade
	1337.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	20x20	144	L bend	
Comment	Package : 1A LQFP 144 20X20X1.4 2 0099183			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	E01A*485XXY				6000000.0	999999.9
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	13.099	mg	supplier	die	Silicon (Si)	7440-21-3		12.627	mg	963967	9444
				supplier	metallization	Aluminium (Al)	7429-90-5		0.056	mg	4275	42
				supplier	metallization	Copper (Cu)	7440-50-8		0.175	mg	13360	131
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	76	1
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.029	mg	2214	22
				supplier	metallization	Titanium (Ti)	7440-32-6		0.005	mg	382	4
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	76	1
				supplier	Passivation	Silicon Oxide	7631-86-9		0.205	mg	15650	153
				Supplier	Leadframe	Copper ( Cu )	7440-50-8		338.955	mg	957500	253519
				Supplier	Leadframe	Nickel ( Ni )	7440-02-0		10.549	mg	29800	7890
Leadframe (C7025 + Ag)	Copper & its alloys	354.000	mg	Supplier	Leadframe	Silicon ( Si )	7440-21-3		2.301	mg	6500	1721
				Supplier	Leadframe	Magnesium ( Mg )	7439-95-4		0.531	mg	1500	397
				Supplier	Leadframe	Silver (Ag)	7440-22-4		1.664	mg	4700	1244
				Supplier	Glue or tape	Silver Powder	7440-22-4		1.986	mg	764000	1486
				Supplier	Glue or tape	Bisphenol F Type Epoxy Resin	9003-36-5		0.078	mg	30000	58
Glue epoxy (CRM-1076WA)	Precious metals	2.600	mg	Supplier	Glue or tape	Epoxy resin	Proprietary		0.156	mg	60000	117
				Supplier	Glue or tape	Hardener	Proprietary		0.078	mg	30000	58
				Supplier	Glue or tape	Ethylene dimethacrylate	97-90-5		0.195	mg	75000	146
				Supplier	Glue or tape	1,4-Cyclohexanedimethanol diglycidyl ether	14228-73-0		0.078	mg	30000	58
				Supplier	Glue or tape	Dicyandiamide	461-58-5		0.014	mg	5500	11
				Supplier	Glue or tape	1,1-Di(t-butylperoxy)cyclohexane	3006-86-8		0.014	mg	5500	11
				Supplier	Bonding wire	Gold	7440-57-5		3.657	mg	988500	2736
				Supplier	Bonding wire	Palladium	7440-05-3		0.043		11500	32
Encapsulation (EME-G6315H)	M-011 Other inorganic materials	952.100	mg	Supplier	Molding Compound	2,2'-(3,3',5,5'-Tetramethyl-(1,1'-biphenyl))-4,4'	85954-11-6		38.084	mg	40000	28485
				Supplier	Molding Compound	Epoxy resin	Proprietary		19.042	mg	20000	14242
				Supplier	Molding Compound	Phenol Resin	Proprietary		71.408	mg	75000	53409
				Supplier	Molding Compound	Silica(Amorphous) A	60676-86-0		675.515	mg	709500	505247
				Supplier	Molding Compound	Silica(Amorphous) B	7631-86-9		142.815	mg	150000	106818
				Supplier	Molding Compound	Carbon black	1333-86-4		5.237	mg	5500	3917
External Plating (Sn)	M-011 Other inorganic materials	11.500	mg	Supplier	Matte Sn	Tin (Sn)	7440-31-5		11.499	mg	999900	8600
				Supplier	Matte Sn	Impurities	-		0.001	mg	100	1